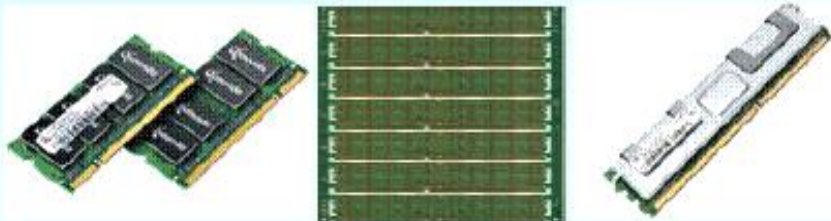


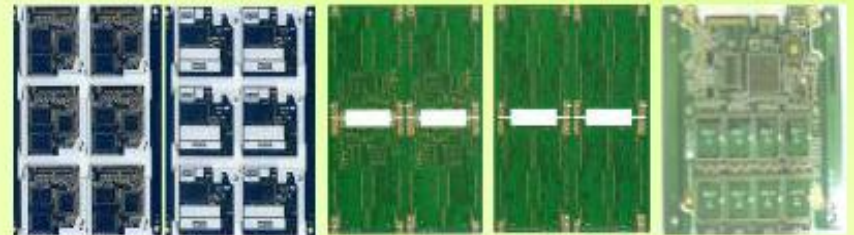
### Memory Module Board (MMB)

- 4L, 6L, 8L, 10L, 12L
- DDR, DDR II, DDR III, FB-DIMM
- U-DIMM, R-DIMM, VLP DIMM, SO-DIMM
- Standard type, Sequential build-up type



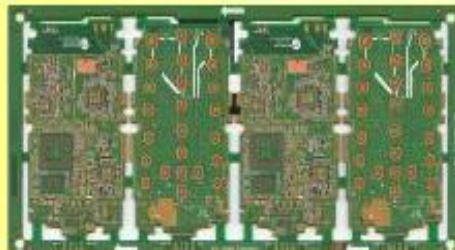
### Solid State Drive (SSD)

- 4L, 6L, 8L
- Halogen Free / Low CTE core material
- TCP type, BGA type Controller
- ENIG / OSP Surface Finish



### Mobile Phone Board

- 1-C-1 type, 2-C-2 type
- Halogen Free core material
- Copper filled via ( Stacked via )
- B2IT build-up



### Others

- Display, Network Board, BIB
- Max. Board Thickness 3.2 mm
- Via in Pad, Build-up type
- ENIG / Immersion Tin Surface Finish

